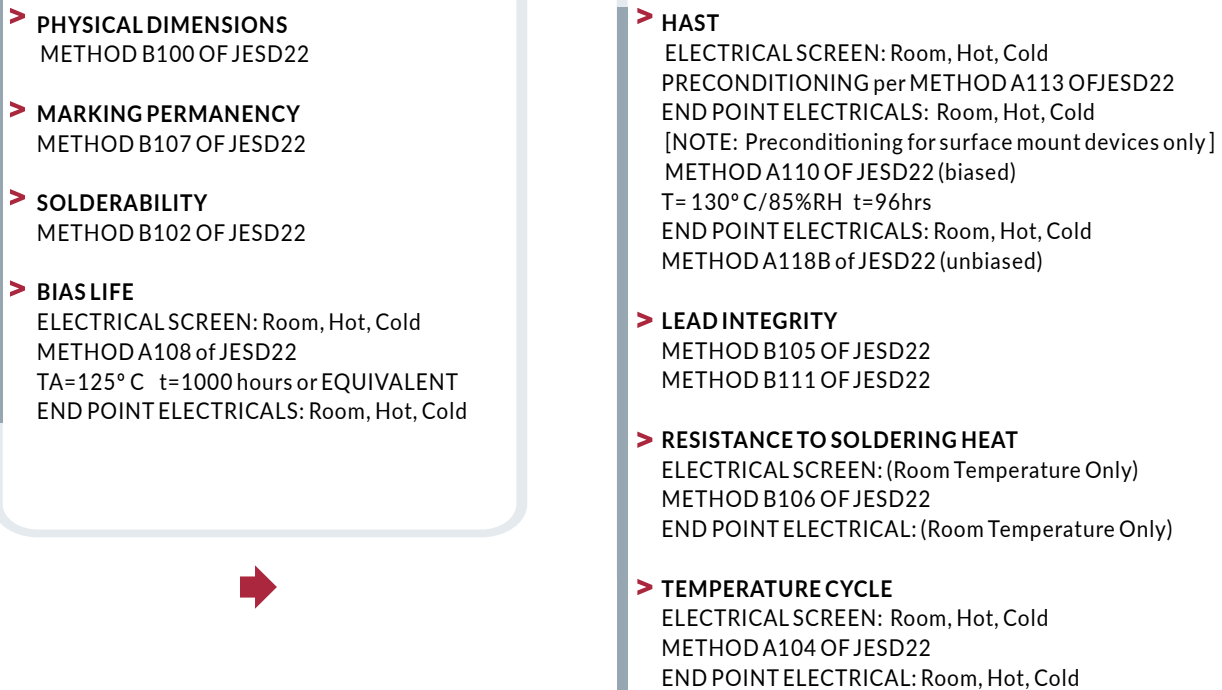


# Qualification Summaries

\*Performed at Rochester's Newburyport campus when appropriate. \*\*Performed at Rochester's Newburyport campus.

## Plastic Packages

- 
- > **PHYSICAL DIMENSIONS**  
METHOD B100 OF JESD22
  - > **MARKING PERMANENCY**  
METHOD B107 OF JESD22
  - > **SOLDERABILITY**  
METHOD B102 OF JESD22
  - > **BIAS LIFE**  
ELECTRICAL SCREEN: Room, Hot, Cold  
METHOD A108 of JESD22  
TA=125° C t=1000 hours or EQUIVALENT  
END POINT ELECTRICALS: Room, Hot, Cold
  - > **HAST**  
ELECTRICAL SCREEN: Room, Hot, Cold  
PRECONDITIONING per METHOD A113 OF JESD22  
END POINT ELECTRICALS: Room, Hot, Cold  
[NOTE: Preconditioning for surface mount devices only]  
METHOD A110 OF JESD22 (biased)  
T= 130° C/85%RH t=96hrs  
END POINT ELECTRICALS: Room, Hot, Cold  
METHOD A118B of JESD22 (unbiased)
  - > **LEAD INTEGRITY**  
METHOD B105 OF JESD22  
METHOD B111 OF JESD22
  - > **RESISTANCE TO SOLDERING HEAT**  
ELECTRICAL SCREEN: (Room Temperature Only)  
METHOD B106 OF JESD22  
END POINT ELECTRICAL: (Room Temperature Only)
  - > **TEMPERATURE CYCLE**  
ELECTRICAL SCREEN: Room, Hot, Cold  
METHOD A104 OF JESD22  
END POINT ELECTRICAL: Room, Hot, Cold

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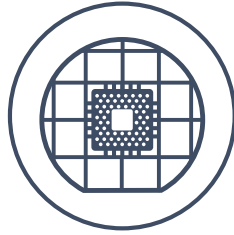


# The Semiconductor Lifecycle Solution™

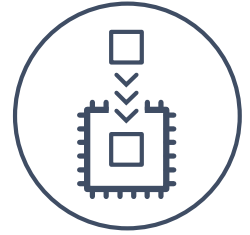
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Inventory Distribution



Product Manufacturing



Manufacturing Services

